

Abstract

Provided are an epoxy resin, a polyvalent hydroxy resin, and a composition thereof, which are excellent in curability, provide a cured product excellent in mechanical strength, flame retardancy, moisture resistance, low elasticity, and the like, and are suitable for applications such as sealing of electrical and electronic parts, and circuit board materials. The polyvalent hydroxy resin is an aralkyl-modified polyvalent hydroxy resin, which is obtained by subjecting a narrowly dispersed polyvalent hydroxy compound including 15% or less of $n=1$ component and 50% or more of a total of $n=2$ and $n=3$ components and having an M_w/M_n of 1.2 or less to a reaction with an aralkylating agent such as a styrene. The epoxy resin is obtained by subjecting the aralkyl-modified polyvalent hydroxy resin to a reaction with epichlorohydrin. Further, the composition is an epoxy resin composition including the aralkyl-modified polyvalent hydroxy resin or the epoxy resin as an essential component.